



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

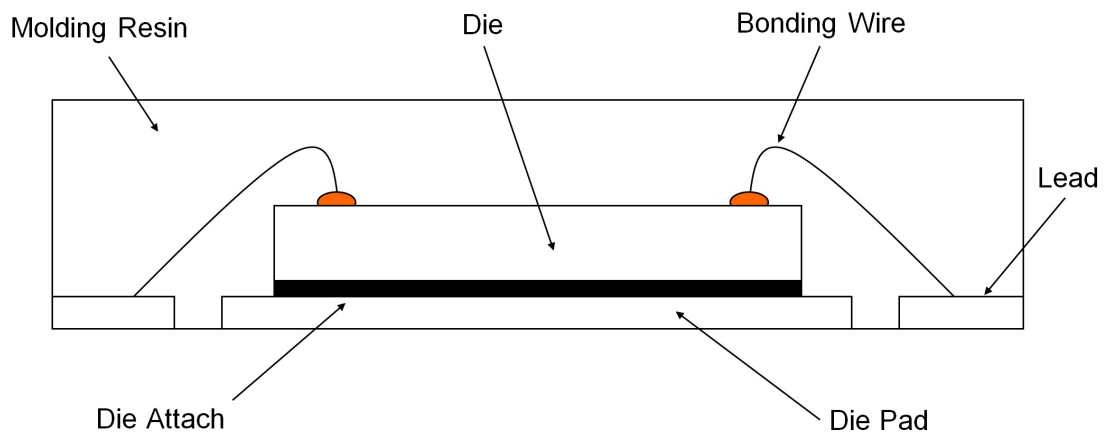
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## 1. Package Information

Package Name	VQFN024V4040
Type	QFN
Pin Count	24
Outline Dimension	EX463-5001-2
Drawing No.	
Package Weight [g]	0.04
Lead Finish	Pure Tin
MSL Level	Level1

## 2. Package Structure



3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

Packing Form		Tape&Reel
Packing Quantity	[pcs]	2500
PIN 1 Orientation		E2

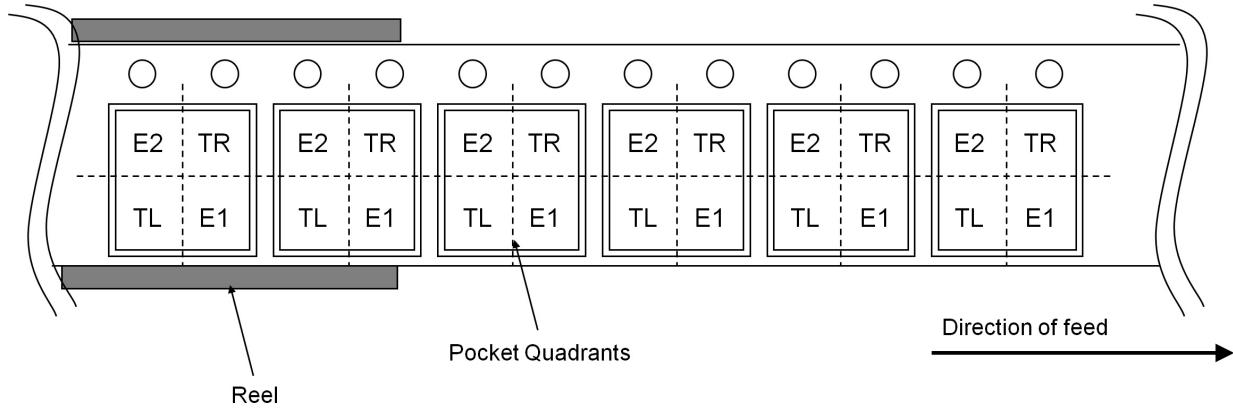


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

E2 : PIN1 is placed to the top left corner.

TR : PIN1 is placed to the top right corner.

TL : PIN1 is placed to the lower left.

E1 : PIN1 is placed to the lower right.

3.2 Use material

Item	Material
Embossed carrier tape	PS
Cover tape	PET+PE
Reel	PS
Unit box	Cardboard
Shipping box	Cardboard

3.3 Leader specification

No component pockets are 200 mm or more.

3.4 Trailer specification

No component pockets are 80 mm or more. Tape is free from reel.

3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

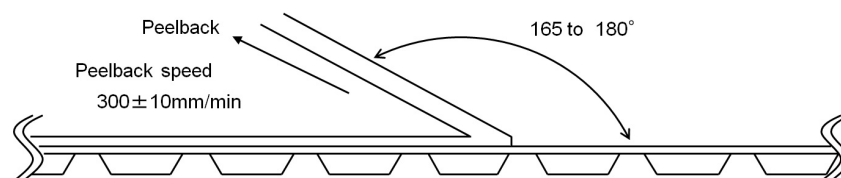


Fig. 2 Test method

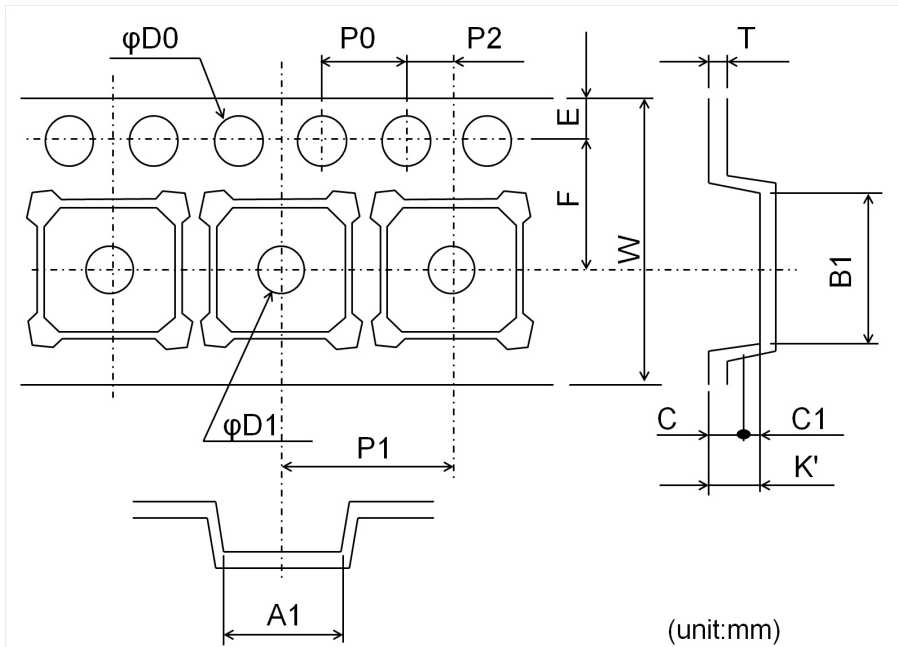
3.6 Missing lcs

(1) No consecutive dropouts.

(2) A maximum 0.1 % of specified number of products in each packing may be missing.

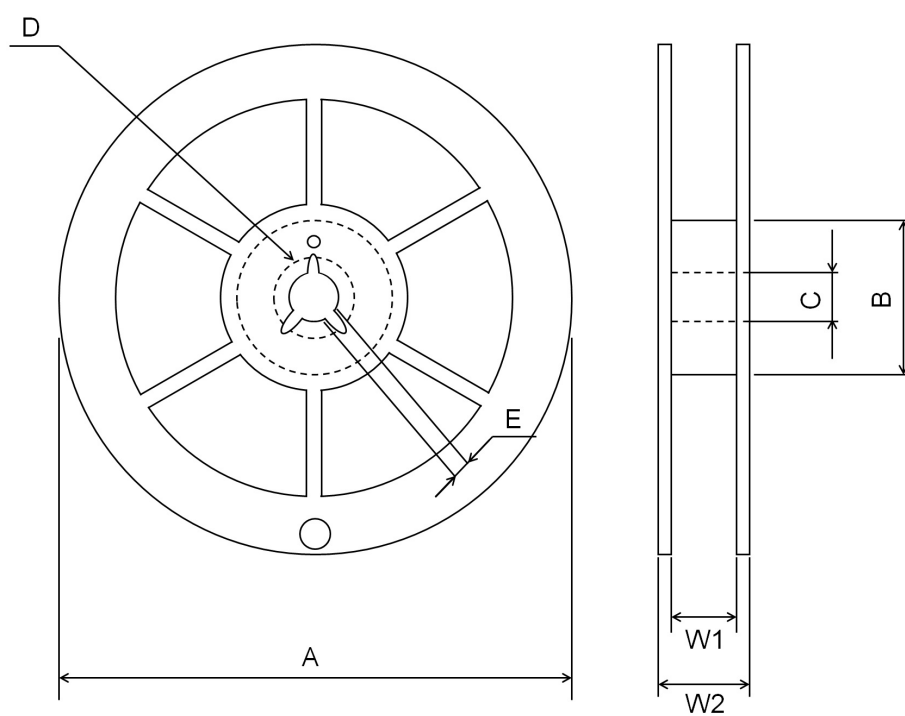
3.7 Tape and Reel Specification

3.7.1 Tape Dimension



	Tape Dimension	Tape Tolerance
A1	4.20	$\pm 0.05$
B1	4.20	$\pm 0.05$
C	1.15	-
C1	0.65	-
D0	$\phi 1.5$	$+0.1/-0$
D1	$\phi 1.5$	$\pm 0.1$
E	1.75	$\pm 0.1$
F	5.50	$\pm 0.05$
K'	1.80	$\pm 0.1$
P0	4.00	$\pm 0.1$
P1	8.00	$\pm 0.1$
P2	2.00	$\pm 0.05$
T	0.30	$\pm 0.05$
W	12.0	$\pm 0.2$

## 3.7.2 Reel Dimension

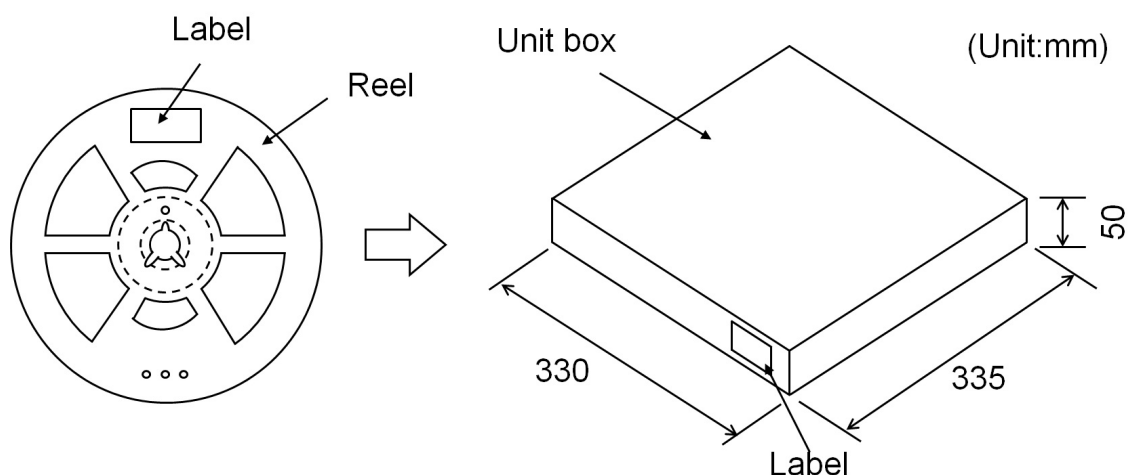


(unit:mm)

	Reel Dimension	Reel Tolerance
A	330	±2.0
B	80	±1.0
C	13	±0.2
D	21	±0.8
E	2	±0.5
W1	13.5	±1.0
W2	17.5	±1.0

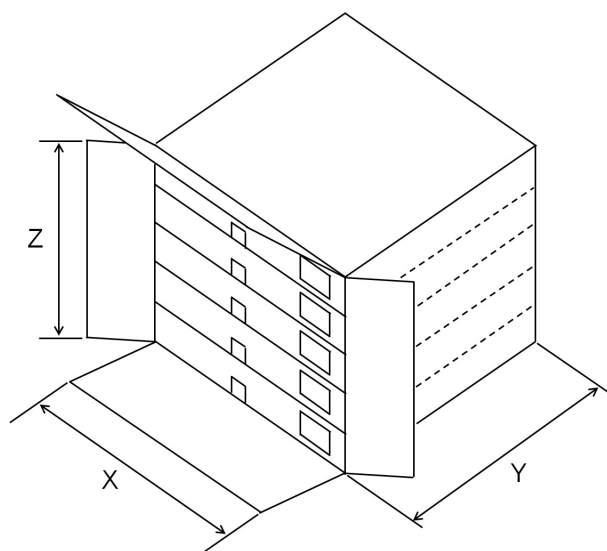
3.8 Packing Method

1 reel(s) or less per unit box



3.9 Packing Style

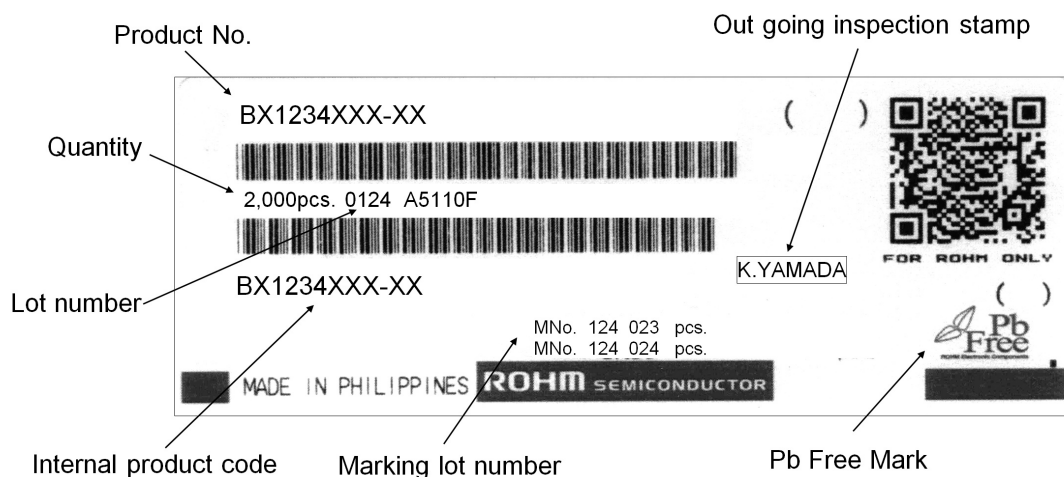
5 unit boxes or less per shipping box



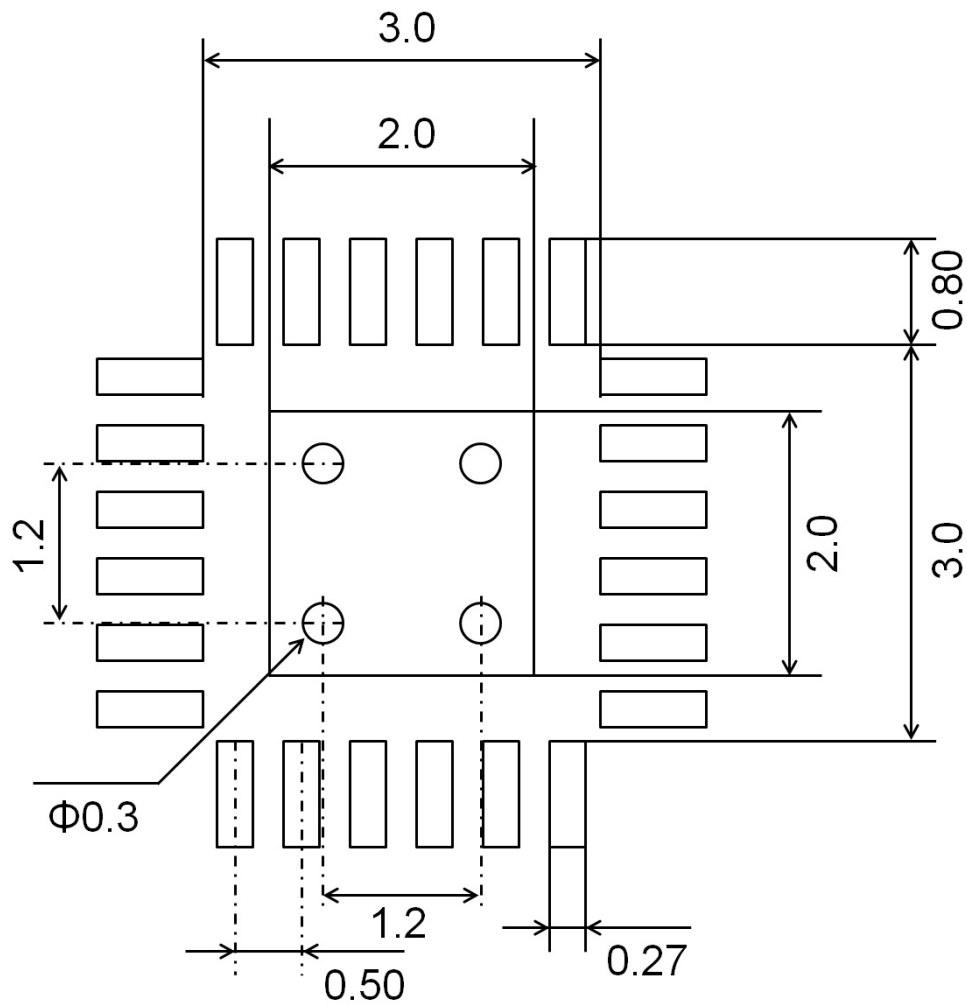
(unit:mm)

Shipping Box Dimension	
X	347
Y	353
Z	287

3.10 Label Specification



4. Footprint dimensions

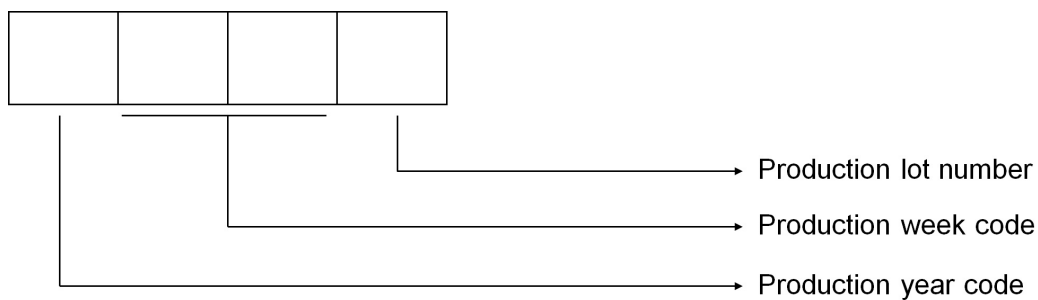


(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.



## 5. Marking Specification



## 6. Storage conditions

## 6.1 Storage environment

## Recommended storage conditions

	Min.	Max.	Unit
Temperature	5	30	°C
Humidity	40	70	% RH

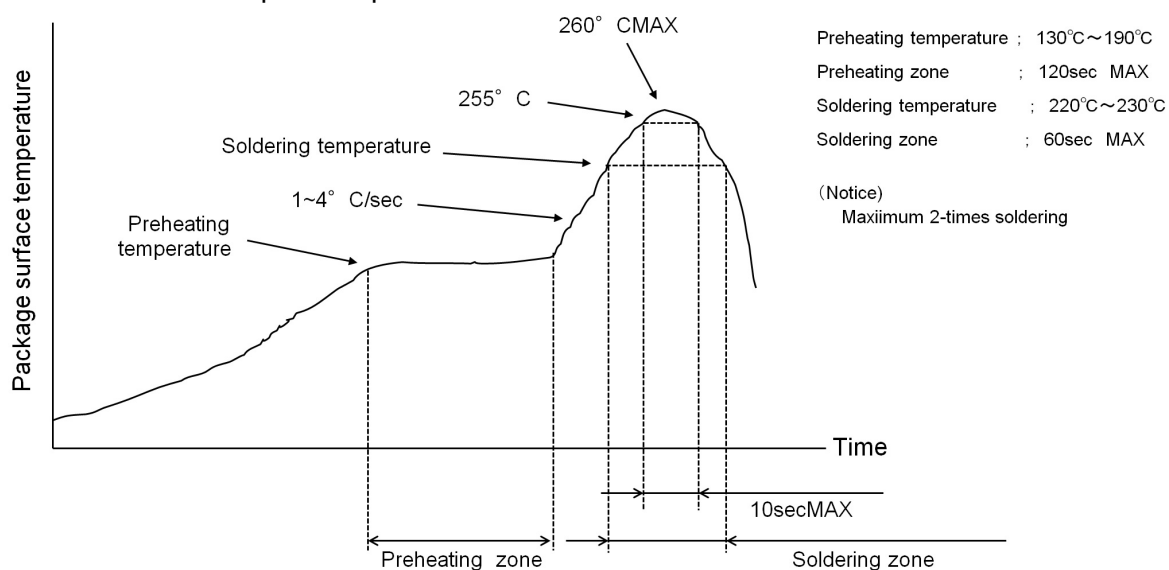
## 6.2 Storage period

	Min.	Max.	Unit
Storage period	-	1	year



7. Soldering conditions

7.1 Recommended temperature profile for reflow

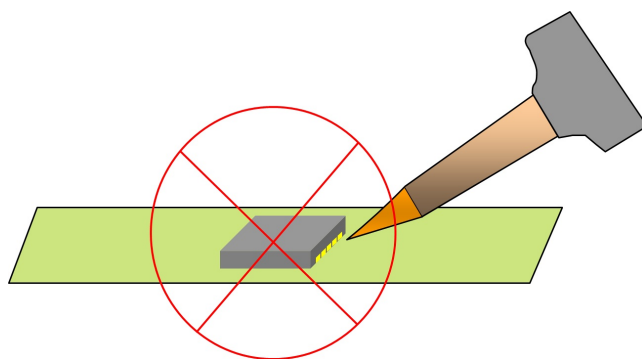


7.2 For wave soldering

The wave soldering method is not supported.

7.3 For solder iron

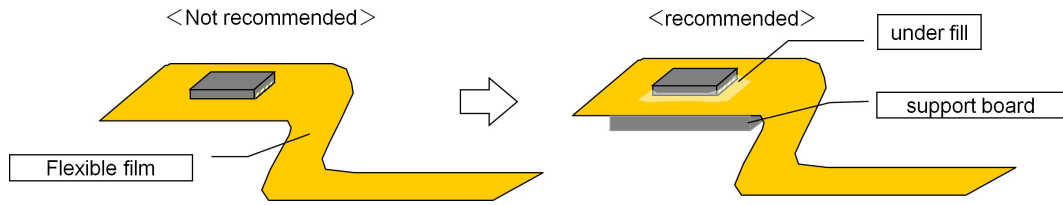
Rework by soldering iron is not allowed or it may cause mold crack and terminal open.



7.4 Caution for solder mounting

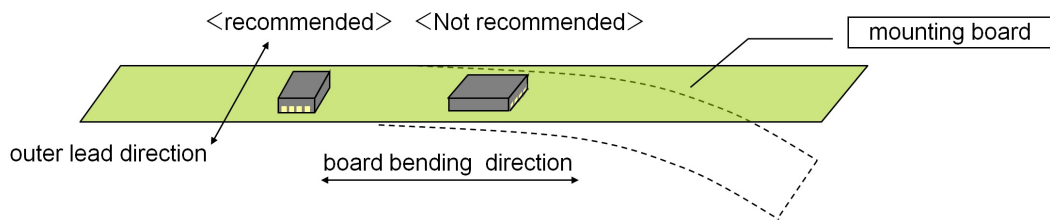
7.4.1 For mounting on flexible film

Mounting on flexible film, film bend may occur lack of lead from package, usage of support board and under fill is recommended.



7.4.2 For Mounting long and narrow board

Mounting on long and narrow board, bending stress may occur a lack of lead from package, bending board direction and outer lead direction is recommended as drawing (vertically layout) and under fill usage is recommended.



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